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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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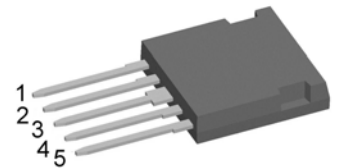
## Standard Rectifier

<b>3~ Rectifier</b>	
$V_{RRM}$	= 1600 V
$I_{DAV}$	= 30 A
$I_{FSM}$	= 150 A


### 3~ Rectifier Bridge

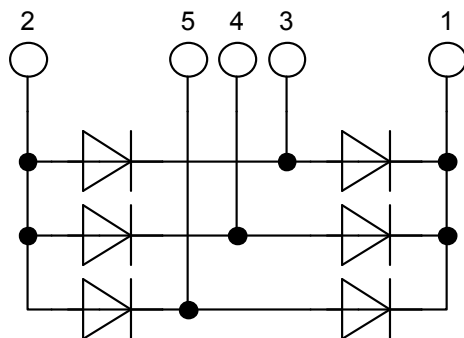
Part number

FUO22-16N



Backside: isolated

 E72873



#### Features / Advantages:

- Package with DCB ceramic
- Reduced weight
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current

#### Applications:

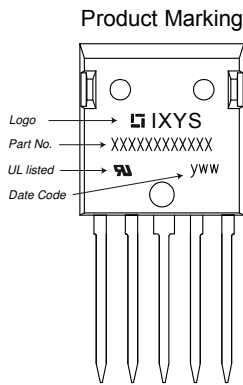
- Diode for main rectification
- For single and three phase bridge configurations

#### Package: i4-Pac

- Isolation Voltage: 3000V~
- Industry convenient outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Soldering pins for PCB mounting
- Backside: DCB ceramic
- Reduced weight
- Advanced power cycling

Rectifier				Ratings				
Symbol	Definition	Conditions		min.	typ.	max.	Unit	
$V_{RSM}$	max. non-repetitive reverse blocking voltage					1700	V	
$V_{RRM}$	max. repetitive reverse blocking voltage					1600	V	
$I_R$	reverse current, drain current	$V_R = 1600$ V	$T_{VJ} = 25^\circ\text{C}$			10	$\mu\text{A}$	
		$V_R = 1600$ V	$T_{VJ} = 150^\circ\text{C}$			1	mA	
$V_F$	forward voltage drop	$I_F = 10$ A	$T_{VJ} = 25^\circ\text{C}$			1.20	V	
						1.62	V	
		$I_F = 30$ A	$T_{VJ} = 150^\circ\text{C}$			1.12	V	
						1.73	V	
$I_{DAV}$	bridge output current	$T_C = 120^\circ\text{C}$ rectangular	$T_{VJ} = 175^\circ\text{C}$			30	A	
								$d = \frac{1}{3}$
$V_{FO}$	threshold voltage					0.81	V	
$r_F$	slope resistance					31	m $\Omega$	
$R_{thJC}$	thermal resistance junction to case					3	K/W	
$R_{thCH}$	thermal resistance case to heatsink				0.20		K/W	
$P_{tot}$	total power dissipation			$T_C = 25^\circ\text{C}$		50	W	
$I_{FSM}$	max. forward surge current	$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 45^\circ\text{C}$			150	A	
								$t = 8,3$ ms; (60 Hz), sine
		$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 150^\circ\text{C}$				130	A
$I^2t$	value for fusing	$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 45^\circ\text{C}$			115	A <sup>2</sup> s	
								$t = 8,3$ ms; (60 Hz), sine
		$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 150^\circ\text{C}$				85	A <sup>2</sup> s
$C_J$	junction capacitance	$V_R = 400$ V; $f = 1$ MHz		$T_{VJ} = 25^\circ\text{C}$		4	pF	

Package i4-Pac		Ratings				
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per terminal			35	A
$T_{stg}$	storage temperature		-55		150	°C
$T_{VJ}$	virtual junction temperature		-55		175	°C
<b>Weight</b>				9		g
$F_C$	mounting force with clip		20		120	N
$d_{Spp/App}$	creepage distance on surface   striking distance through air	terminal to terminal	1.7			mm
$d_{Spb/Apb}$		terminal to backside	5.1			mm
$V_{ISOL}$	isolation voltage	t = 1 second	3000			V
		t = 1 minute	2500			V

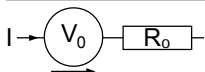


Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	FUO22-16N	FUO22-16N	Tube	25	500357

### Equivalent Circuits for Simulation

\* on die level

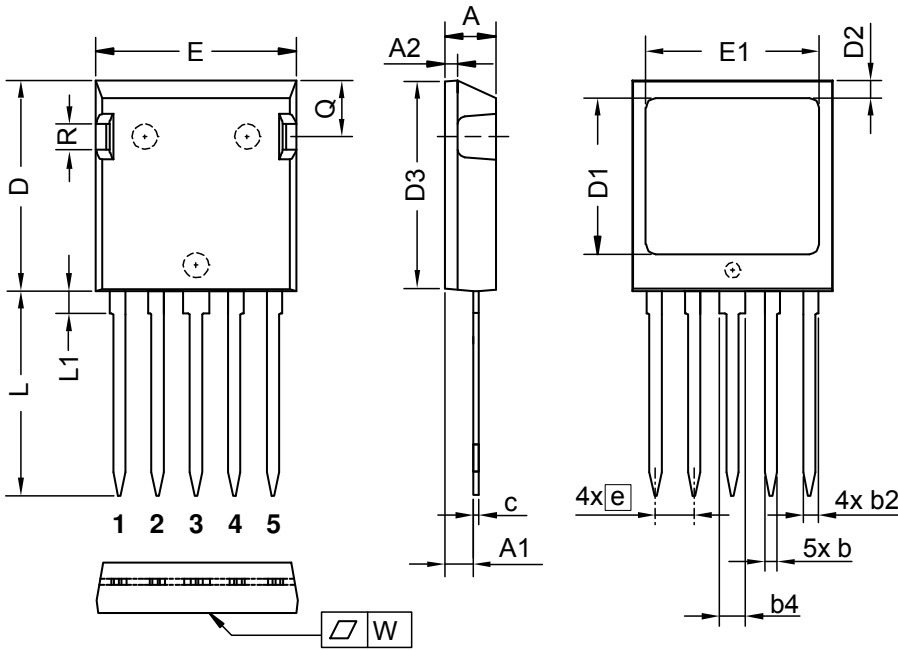
$T_{VJ} = 175^{\circ}C$



Rectifier

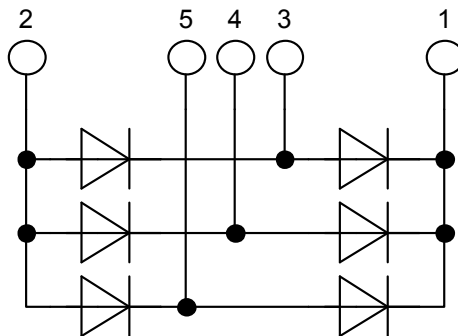
$V_{0\ max}$	threshold voltage	0.81	V
$R_{0\ max}$	slope resistance *	28	mΩ

## Outlines i4-Pac



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.83	5.21	0.190	0.205
A1	2.59	3.00	0.102	0.118
A2	1.17	2.16	0.046	0.085
b	1.14	1.40	0.045	0.055
b2	1.47	1.73	0.058	0.068
b4	2.54	2.79	0.100	0.110
c	0.51	0.74	0.020	0.029
D	20.80	21.34	0.819	0.840
D1	14.99	15.75	0.590	0.620
D2	1.65	2.03	0.065	0.080
D3	20.30	20.70	0.799	0.815
E	19.56	20.29	0.770	0.799
E1	16.76	17.53	0.660	0.690
e	3.81 BSC		0.150 BSC	
L	19.81	21.34	0.780	0.840
L1	2.11	2.59	0.083	0.102
Q	5.33	6.20	0.210	0.244
R	2.54	4.57	0.100	0.180
W	-	0.10	-	0.004

Die konvexe Form des Substrates ist typ. < 0.05 mm über der Kunststoffoberfläche der Bauteilunterseite  
 The convex bow of substrate is typ. < 0.05 mm over plastic surface level of device bottom side



**Rectifier**

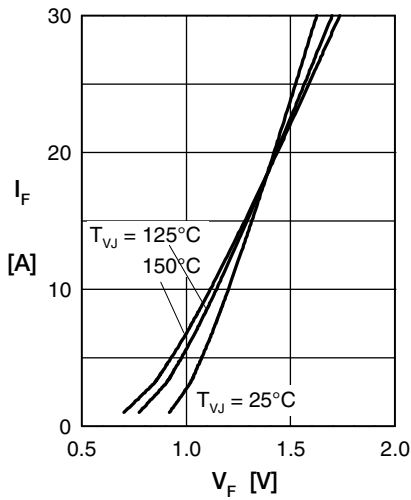


Fig. 1 Forward current versus voltage drop per diode

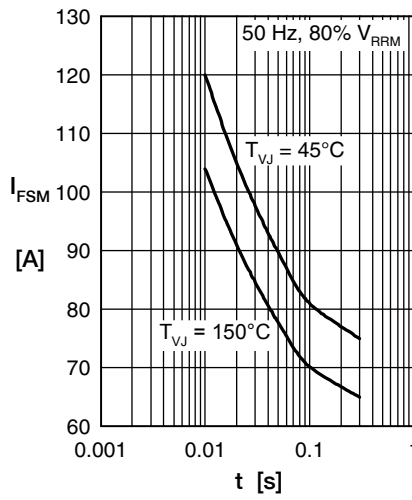


Fig. 2 Surge overload current

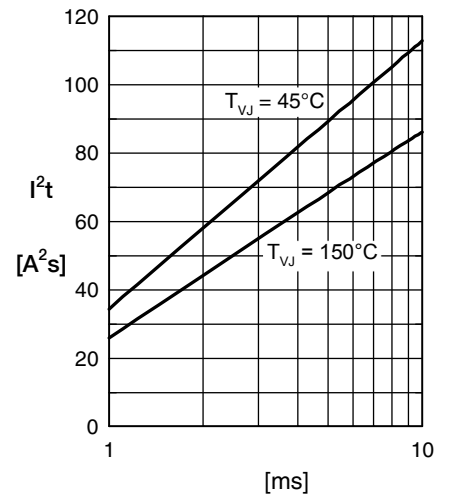


Fig. 3  $I^2t$  versus time per diode

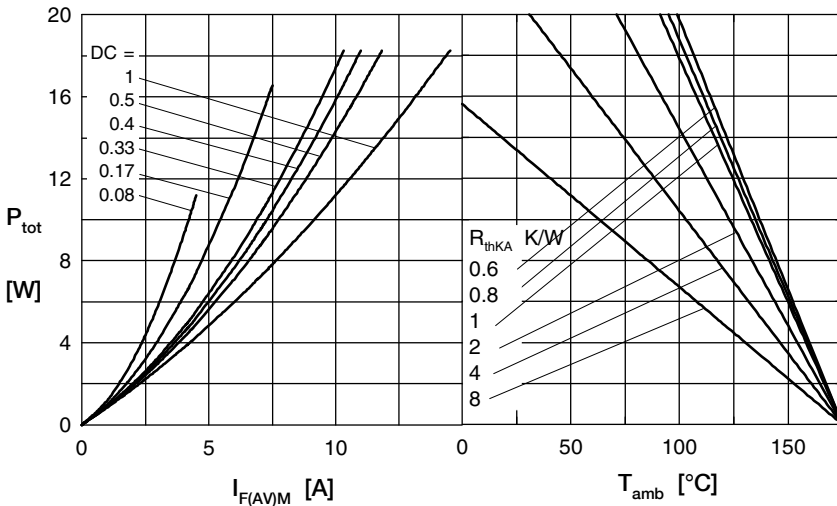


Fig. 4 Power dissipation vs. direct output current & ambient temperature

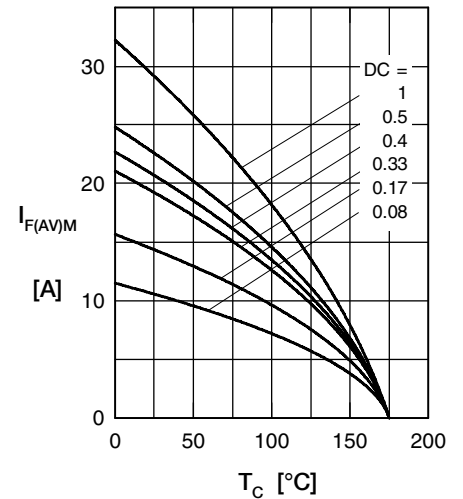


Fig. 5 Max. forward current vs. case temperature

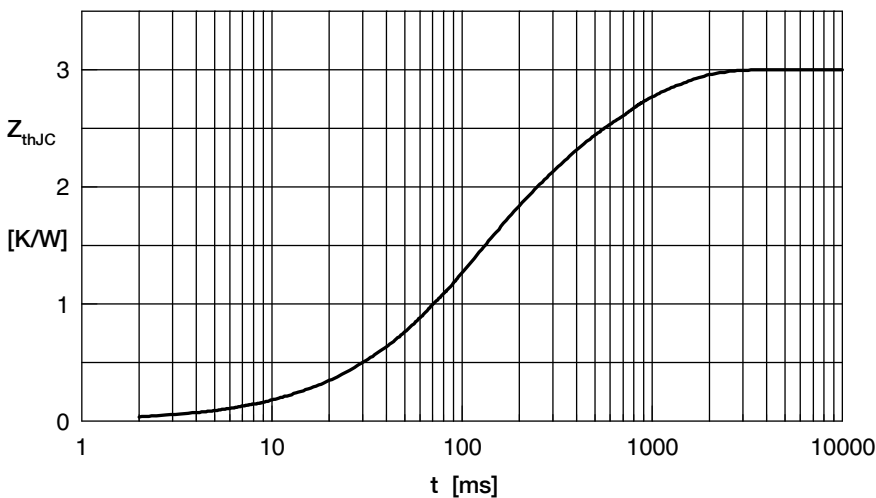


Fig. 6 Transient thermal impedance junction to case

Constants for  $Z_{thJC}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	1.359	0.1015
2	0.3286	0.1026
3	0.4651	0.4919
4	0.8473	0.62